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Amendments to the Claims

Claims 1-93 (Canceled)

Claim 94 (Previously Presented) An apparatus for processing a substrate, said apparatus comprising:

a plating unit having a plating chamber for electroplating a substrate having fine grooves in a surface of the substrate and a seed layer on a surface of the fine grooves; and

an annealing unit having a chamber for annealing the substrate,

wherein said plating unit is structured to form a plated film on the seed layer by electroplating with supplying a first current by a voltage to the seed layer and then supplying a second current to the seed layer.

Claim 95 (Previously Presented) An apparatus according to claim 94, wherein the second current is larger than the first current.

Claim 96 (Previously Presented) An apparatus according to claim 94, wherein said plating unit is structured to apply a reverse voltage to the seed layer for thereby etching the plated film formed on the substrate.

Claims 97 and 98 (Canceled)